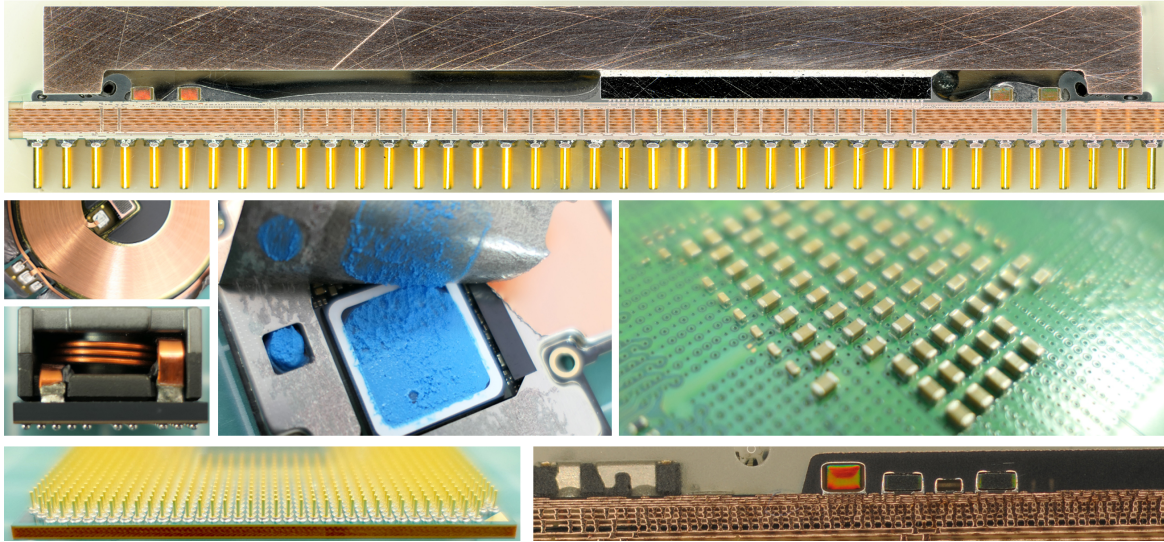


THE SEMICONDUCTOR AND PACKAGING REPORT

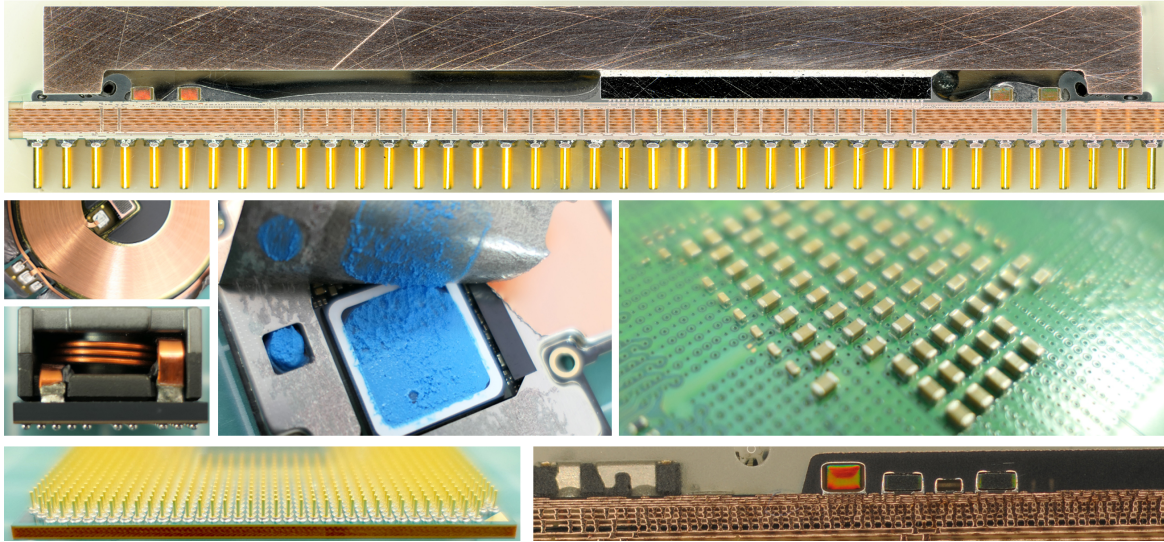
FOURTH QUARTER 2023



- STATE OF THE SEMICONDUCTOR AND PACKAGE BUSINESS : HIGHLIGHTS
- STATE OF THE SEMICONDUCTOR AND PACKAGE BUSINESS
 - Prismark's global economic and electronics forecast for 2023/2024F/2028F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- 2023 SEMICONDUCTOR MARKET REVIEW AND 2024/2028 FORECASTS
 - Review of semiconductor market and package trends for 2023, revised 2024 forecast, and an outlook to 2028. Detailed unit and value forecasts by device type and package type, highlighting the increasing importance of advanced packaging to overall packaging value-add.
- INTEL'S AMBITION IN FOVEROS PACKAGING
 - Intel's introduction of its Core Ultra Meteor Lake processor using Foveros technology is an important milestone in the volume implementation of 2.5D packaging.
- SMARTPHONE AP PACKAGING UPDATE
 - Comparison of most recent APs introduced by Qualcomm and MediaTek
- GLOBAL WAFER CAPACITY AND WAFER PRODUCTION IN CHINA
 - Geopolitical concerns and supply chain resiliency has spawned a wave of global investments in semiconductor fabs. China has moved aggressively to expand its capacity even in the face of semiconductor manufacturing equipment export restrictions.
- UPDATES ON TAIWANESE NOTEBOOK ODMs
 - Updates on key notebook ODMs and their recent business performance and investment activities
- COMPANY NEWS: SEMICONDUCTOR AND WAFER FABRICATION
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- COMPANY NEWS: SEMICONDUCTOR PACKAGING
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

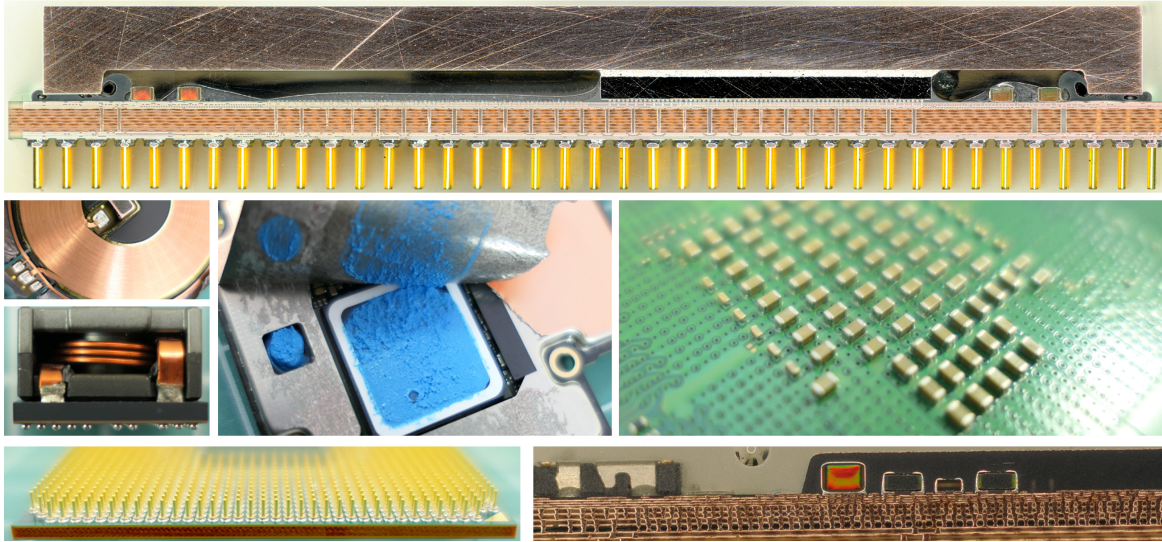
THIRD QUARTER 2023



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update, 2024 Preliminary Forecast, and 2027 Outlook
 - Review of semiconductor market and package trends for 2023, 2024 preliminary forecast, and an outlook to 2027
- IC Packaging Forecast Update
 - A review and forecast for the IC packaging market with an update on the advanced packaging market for mobile phone and server applications
- Updates on Handset Market and Chipset Supply in China
 - Updates on the handset market in China, including the chipset supply chain and local handset suppliers' company news
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

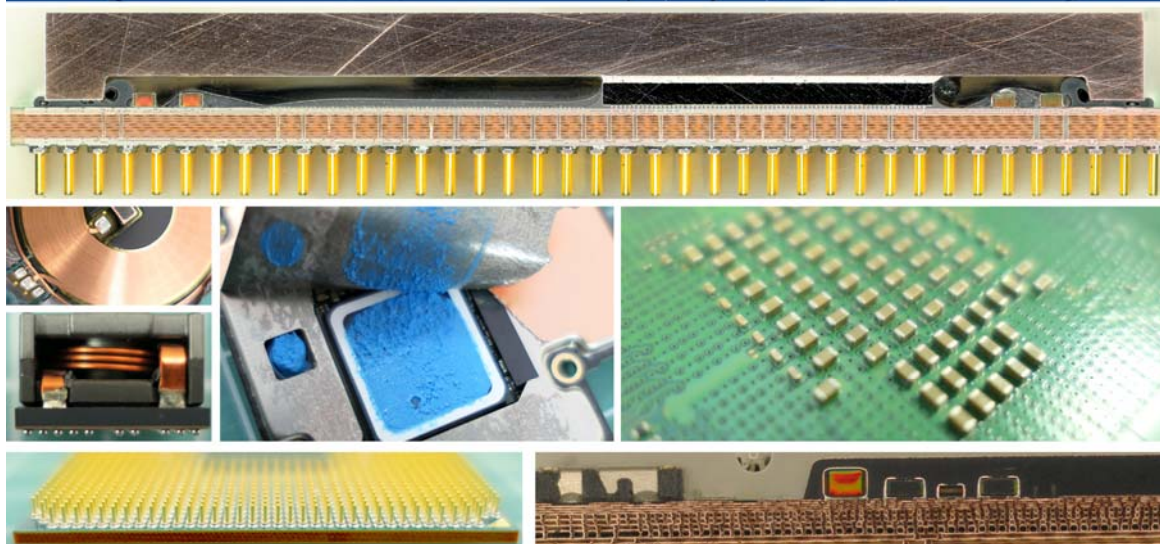
SECOND QUARTER 2023



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update and Revised 2027 Outlook
 - Review of semiconductor market and package trends for 2023 and an outlook to 2027
- Regional Split of Semiconductor Back-End Activity
 - A review and discussion on back-end activities by manufacturing site among the leading IDM and OSAT companies
- Updates on Handset Manufacturing Industry in Greater China
 - Updates on the handset manufacturing industry in Greater China with a focus on the changing ODM landscape
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

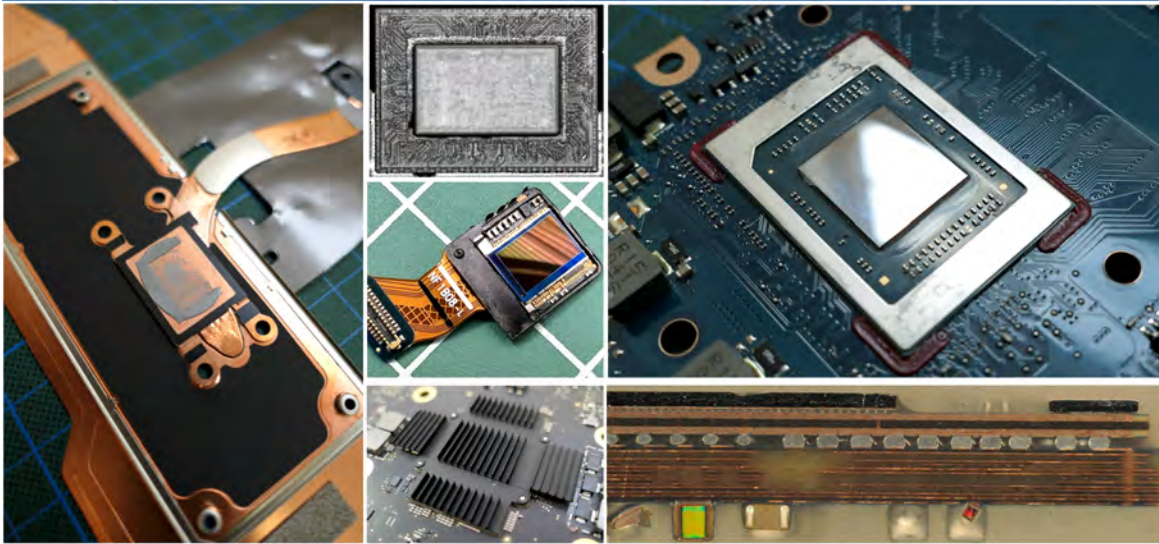
FIRST QUARTER 2023



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update and Revised 2027 Outlook
 - Review of semiconductor market and package trends for 2022, 2023, and an outlook to 2027
- The AI Boom: A Gold Rush Expansion in Advanced Packaging Demand
 - A review and discussion of the impact of the explosive growth in AI servers on advanced packaging. Are we in a bubble?
- Updates on China's Semiconductor Industry
 - Updates on China's semiconductor industry with a focus on the IC design and IC packaging and test segments
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

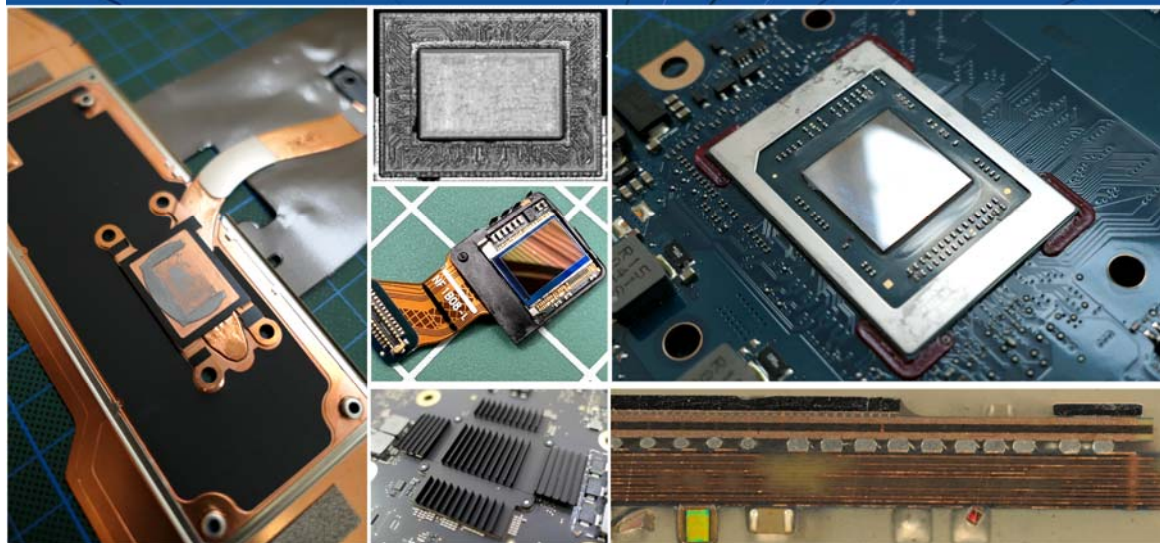
FOURTH QUARTER 2022



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark’s global economic and electronics forecast for 2022 and 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries and preliminary 2023 forecasts and updated Package unit and value forecasts. Includes a refresh of the packaging unit and forecast demand for IC components
- Semiconductor and Packaging: Five-Year Outlook
 - Review of semiconductor market and package trends for 2022, 2023, and an outlook to 2027
- System-in-Package (SiP) Market Update and Technology Outlook
 - An updated review of the fast growth SiP market including stacked CSP, PoP, RF modules, MEMS, Power SiP, and camera modules
- Updates on Taiwanese ODMs (Notebook PCs and Servers)
 - Summary of the world’s leading ODM players for notebook PCs and servers based in Taiwan
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations

THE SEMICONDUCTOR AND PACKAGING REPORT

SECOND QUARTER • AUGUST 2022



- State of the Semiconductor and Package Business
 - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2021 and 2022, including COVID-19 impact and Russia's war in Ukraine; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: Market Update and Revised Outlook
 - Review of semiconductor market and package trends for 2021 and an outlook to 2026
- High-Performance Silicon Packaging: The Importance of Bridge Interconnects and Future Migration to Hybrid Bonding
 - Review of high-performance silicon packaging technology developments and trends
- Updates on China's Semiconductor Industry
 - Overview of China's handset market, production, and chipset development
- Company News: Semiconductor and Wafer Fabrication
 - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
 - Recent developments in packaging at leading OSAT and captive assembly operations



*CONSULTANTS TO THE ELECTRONICS INDUSTRY
BUSINESS OPPORTUNITY FROM TECHNOLOGY AND
MARKET CHANGES*

PRISMARK PARTNERS LLC

This material is © Prismark Partners LLC

130 Main Street, Cold Spring Harbor, NY 11724 USA • Telephone: 631-367-9187 • Fax: 631-367-9223 • e-mail: partners@prismark.com

Visit our website at **www.prismark.com**